

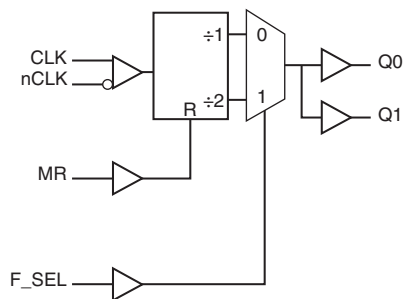
## GENERAL DESCRIPTION

The 87021I is a high performance ÷1/÷2 Differential-to-LVCMOS/LVTTL Clock Generator and a member of the family of High Performance Clock Solutions from IDT. The CLK, nCLK pair can accept most standard differential input levels. Guaranteed part-to-part skew characteristics make the 87021I ideal for those clock distribution applications demanding well defined performance and repeatability.

## FEATURES

- Two single-ended LVCMOS/LVTTL outputs
- One differential CLK, nCLK input pair
- CLK, nCLK pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- Maximum output frequency: 250MHz
- Additive phase jitter, RMS: 0.18ps (typical)
- Output skew: 50ps (maximum)
- Part-to-part skew: 450ps (maximum)
- Propagation delay: 3.4ns (maximum)
- Full 3.3V or 2.5V operating supply
- -40°C to 85°C ambient operating temperature
- Available in lead-free (RoHS 6) package

## BLOCK DIAGRAM



## PIN ASSIGNMENT

|       |   |   |     |
|-------|---|---|-----|
| CLK   | 1 | 8 | VDD |
| nCLK  | 2 | 7 | Q0  |
| MR    | 3 | 6 | Q1  |
| F_SEL | 4 | 5 | GND |

**87021I**

**8-Lead SOIC**

3.90mm x 4.90mm x 1.375mm package body

**M Package**

Top View

**TABLE 1. PIN DESCRIPTIONS**

| Number | Name            | Type   |          | Description   |
|--------|-----------------|--------|----------|---|
| 1      | CLK             | Input  | Pulldown | Non-inverting differential clock input.   |
| 2      | nCLK            | Input  | Pullup   | Inverting differential clock input.   |
| 3      | MR              | Input  | Pulldown | Active High Master Reset. When logic HIGH, the internal dividers are reset causing the outputs to go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTTL interface levels. See Table 3. |
| 4      | F_SEL           | Input  | Pulldown | Selects divider value for Qx outputs as described in Table 3. LVCMOS / LVTTTL interface levels.   |
| 5      | GND             | Power  |          | Power supply ground.  |
| 6      | Q1              | Output |          | Singled-ended output. LVCMOS/LVTTTL interface levels.   |
| 7      | Q0              | Output |          | Singled-ended output. LVCMOS/LVTTTL interface levels.   |
| 8      | V <sub>DD</sub> | Power  |          | Positive supply pin.  |

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**TABLE 2. PIN CHARACTERISTICS**

| Symbol                | Parameter                                  | Test Conditions          | Minimum | Typical | Maximum | Units |
|-----------------------|--|--------------------------|---------|---------|---------|-------|
| C <sub>IN</sub>       | Input Capacitance                          |                          |         | 4       |         | pF    |
| C <sub>PD</sub>       | Power Dissipation Capacitance (per output) | V <sub>DD</sub> = 3.465V |         | 24      |         | pF    |
|                       |  | V <sub>DD</sub> = 2.625V |         | 16      |         | pF    |
| R <sub>PULLUP</sub>   | Input Pullup Resistor                      |                          |         | 51      |         | kΩ    |
| R <sub>PULLDOWN</sub> | Input Pulldown Resistor                    |                          |         | 51      |         | kΩ    |
| R <sub>OUT</sub>      | Output Impedance                           | V <sub>DD</sub> = 3.465V |         | 9       |         | Ω     |

TABLE 3. FUNCTION TABLE

| MR | F_SEL | Divide Value              |
|----|-------|---------------------------|
| 1  | X     | Reset: Q0, Q1 outputs low |
| 0  | 0     | ÷1                        |
| 0  | 1     | ÷2                        |

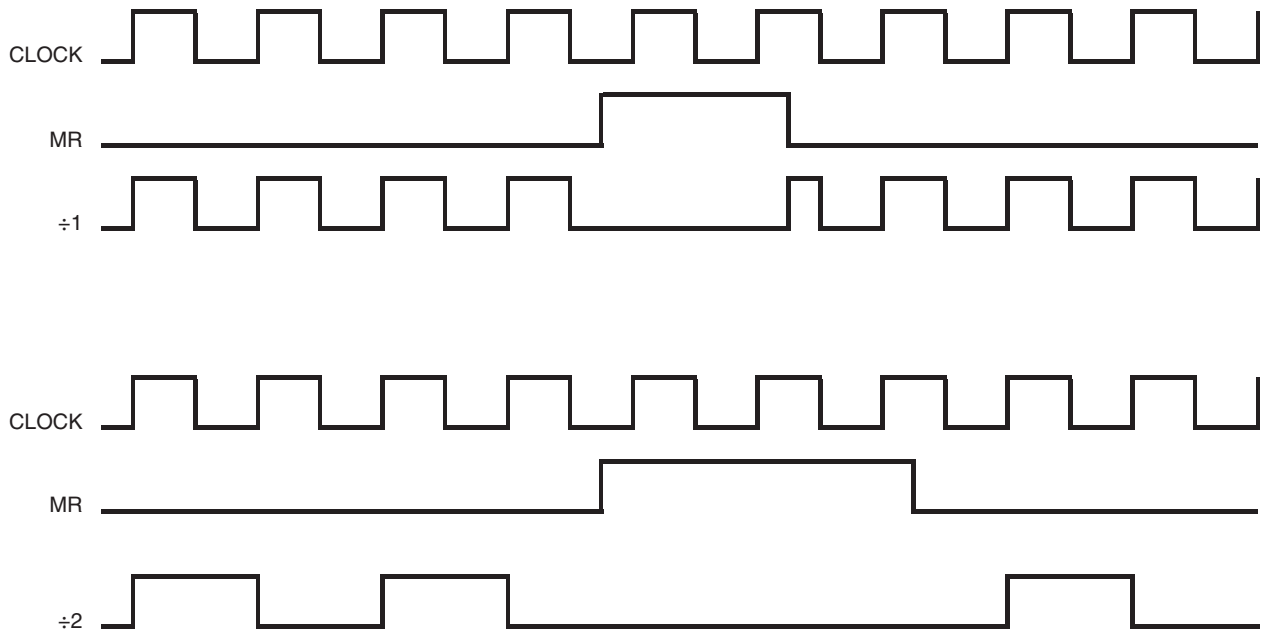


FIGURE 1. TIMING DIAGRAM

**ABSOLUTE MAXIMUM RATINGS**

|  |                          |
|--|--------------------------|
| Supply Voltage, $V_{DD}$                 | 4.6V                     |
| Inputs, $V_I$                            | -0.5V to $V_{DD} + 0.5V$ |
| Outputs, $V_O$                           | -0.5V to $V_{DD} + 0.5V$ |
| Package Thermal Impedance, $\theta_{JA}$ | 103°C/W (0 lfpm)         |
| Storage Temperature, $T_{STG}$           | -65°C to 150°C           |

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 4A. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$** 

| Symbol   | Parameter               | Test Conditions | Minimum | Typical | Maximum | Units |
|----------|-------------------------|-----------------|---------|---------|---------|-------|
| $V_{DD}$ | Positive Supply Voltage |                 | 3.135   | 3.3     | 3.465   | V     |
| $I_{DD}$ | Power Supply Current    |                 |         |         | 60      | mA    |

**TABLE 4B. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = 2.5V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$** 

| Symbol   | Parameter               | Test Conditions | Minimum | Typical | Maximum | Units |
|----------|-------------------------|-----------------|---------|---------|---------|-------|
| $V_{DD}$ | Positive Supply Voltage |                 | 2.375   | 2.5     | 2.625   | V     |
| $I_{DD}$ | Power Supply Current    |                 |         |         | 35      | mA    |

**TABLE 4C. LVCMOS/LVTTL DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$** 

| Symbol   | Parameter                   | Test Conditions                | Minimum | Typical | Maximum        | Units         |
|----------|-----------------------------|--------------------------------|---------|---------|----------------|---------------|
| $V_{IH}$ | Input High Voltage          |                                | 1.3     |         | $V_{DD} + 0.3$ | V             |
| $V_{IL}$ | Input Low Voltage           |                                | -0.3    |         | 0.7            | V             |
| $I_{IH}$ | Input High Current          | $V_{DD} = V_{IN} = 3.465V$     |         |         | 150            | $\mu\text{A}$ |
| $I_{IL}$ | Input Low Current           | $V_{DD} = 3.465V, V_{IN} = 0V$ | -5      |         |                | $\mu\text{A}$ |
| $V_{OH}$ | Output High Voltage; NOTE 1 | $V_{DD} = 3.465V$              | 2.6     |         |                | V             |
| $V_{OL}$ | Output Low Voltage; NOTE 1  | $V_{DD} = 3.465V$ or $2.625V$  |         |         | 0.5            | V             |

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{DD}/2$ . See Parameter Measurement Information section, "3.3V Output Load Test Circuit" diagram.

**TABLE 4D. LVCMOS/LVTTL DC CHARACTERISTICS,  $V_{DD} = 2.5V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$** 

| Symbol   | Parameter                   | Test Conditions                | Minimum | Typical | Maximum        | Units         |
|----------|-----------------------------|--------------------------------|---------|---------|----------------|---------------|
| $V_{IH}$ | Input High Voltage          |                                | 1.1     |         | $V_{DD} + 0.3$ | V             |
| $V_{IL}$ | Input Low Voltage           |                                | -0.3    |         | 0.5            | V             |
| $I_{IH}$ | Input High Current          | $V_{DD} = V_{IN} = 2.625V$     |         |         | 150            | $\mu\text{A}$ |
| $I_{IL}$ | Input Low Current           | $V_{DD} = 2.625V, V_{IN} = 0V$ | -5      |         |                | $\mu\text{A}$ |
| $V_{OH}$ | Output High Voltage; NOTE 1 | $V_{DD} = 2.625V$              | 1.8     |         |                | V             |
| $V_{OL}$ | Output Low Voltage; NOTE 1  | $V_{DD} = 2.625V$              |         |         | 0.5            | V             |

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{DD}/2$ . See Parameter Measurement Information section, "2.5V Output Load Test Circuit" diagram.

**TABLE 4E. DIFFERENTIAL DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$  OR  $V_{DD} = 2.5V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$** 

| Symbol    | Parameter                            | Test Conditions | Minimum                                       | Typical | Maximum         | Units   |
|-----------|--------------------------------------|-----------------|---|---------|-----------------|---------|
| $I_{IH}$  | Input High Current                   | CLK             | $V_{DD} = V_{IN} = 3.465V$ or $2.625V$        |         | 150             | $\mu A$ |
|           |                                      | nCLK            | $V_{DD} = V_{IN} = 3.465V$ or $2.625V$        |         | 5               | $\mu A$ |
| $I_{IL}$  | Input Low Current                    | CLK             | $V_{DD} = 3.465V$ or $2.625V$ , $V_{IN} = 0V$ | -5      |                 | $\mu A$ |
|           |                                      | nCLK            | $V_{DD} = 3.465V$ or $2.625V$ , $V_{IN} = 0V$ | -150    |                 | $\mu A$ |
| $V_{PP}$  | Peak-to-Peak Input Voltage           |                 | 0.15  |         | 1.3             | V       |
| $V_{CMR}$ | Common Mode Input Voltage;<br>NOTE 1 |                 | GND + 0.5                                     |         | $V_{DD} - 0.85$ | V       |

NOTE 1: Common mode voltage is defined as  $V_{IH}$ .

**TABLE 5A. AC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$** 

| Symbol      | Parameter  | Test Conditions                             | Minimum | Typical | Maximum | Units |
|-------------|--|---|---------|---------|---------|-------|
| $f_{MAX}$   | Output Frequency   |   |         |         | 250     | MHz   |
| $t_{PD}$    | Propagation Delay;<br>NOTE 1   | CLK to Qx                                   | 2.1     |         | 3.4     | ns    |
| tjit        | Buffer Additive Phase Jitter, RMS;<br>refer to Additive Phase Jitter Section | 250MHz, Integration Range:<br>12kHz – 20MHz |         | 0.18    |         | ps    |
| tsk(pp)     | Part-to-Part Skew; NOTE 2, 3   |   |         |         | 450     | ps    |
| tsk(o)      | Output Skew; NOTE 3, 4   |   |         |         | 50      | ps    |
| $t_R / t_F$ | Output Rise/Fall Time  | 20% to 80%                                  | 250     |         | 700     | ps    |
| odc         | Output Duty Cycle;<br>NOTE 5   | $F_{out} \leq 133MHz$                       | 45      |         | 55      | %     |
|             |  | $F_{out} > 133MHz$                          | 40      |         | 60      | %     |

NOTE 1: Measured from the differential input crossing point to the output at  $V_{DD}/2$ .

NOTE 2: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DD}/2$ .

NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 4: Defined as skew between outputs at the same supply voltage and with equal load conditions.

NOTE 5: Output Duty Cycle assuming 50% input duty cycle.

**TABLE 5B. AC CHARACTERISTICS,  $V_{DD} = 2.5V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$** 

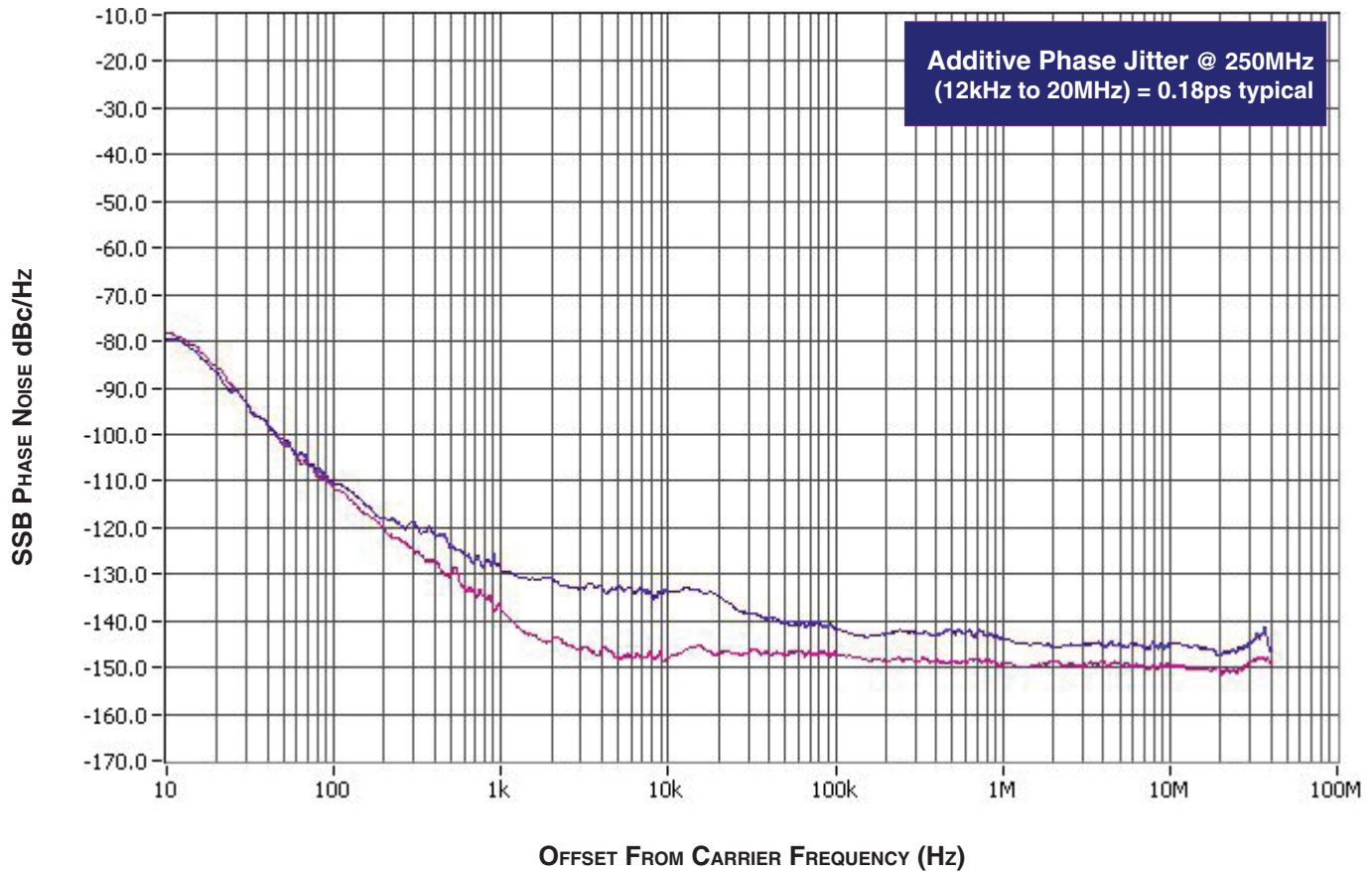
| Symbol      | Parameter  | Test Conditions                             | Minimum | Typical | Maximum | Units |
|-------------|--|---|---------|---------|---------|-------|
| $f_{MAX}$   | Output Frequency   |   |         |         | 250     | MHz   |
| $t_{PD}$    | Propagation Delay;<br>NOTE 1   | CLK to Qx                                   | 2.7     |         | 3.4     | ns    |
| tjit        | Buffer Additive Phase Jitter, RMS;<br>refer to Additive Phase Jitter Section | 250MHz, Integration Range:<br>12kHz – 20MHz |         | 0.3     |         | ps    |
| tsk(pp)     | Part-to-Part Skew; NOTE 2, 3   |   |         |         | 450     | ps    |
| tsk(o)      | Output Skew; NOTE 3, 4   |   |         |         | 25      | ps    |
| $t_R / t_F$ | Output Rise/Fall Time  | 20% to 80%                                  | 250     |         | 700     | ps    |
| odc         | Output Duty Cycle;<br>NOTE 5   | $F_{out} \leq 133MHz$                       | 45      |         | 55      | %     |
|             |  | $F_{out} > 133MHz$                          | 40      |         | 60      | %     |

For NOTES, please see above Table 5A.

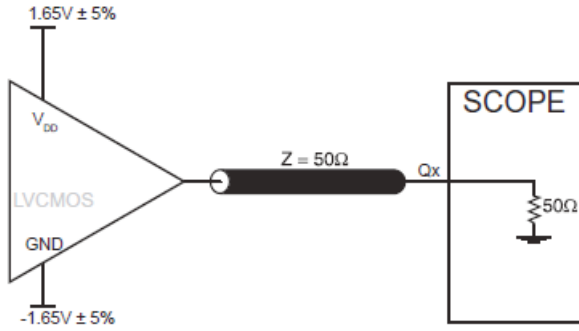
## ADDITIVE PHASE JITTER

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the **dBc Phase Noise**. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels

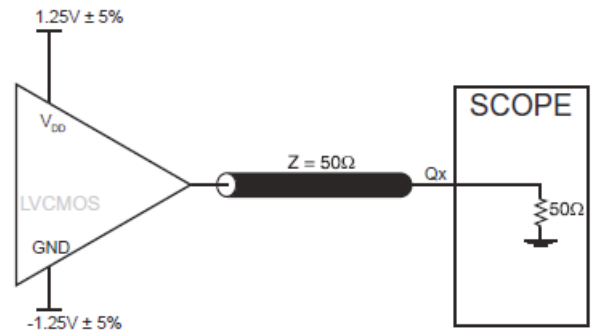
(dBm) or a ratio of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a **dBc** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



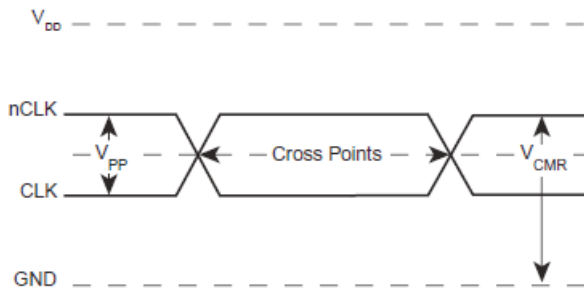
# PARAMETER MEASUREMENT INFORMATION



**3.3V OUTPUT LOAD AC TEST CIRCUIT**



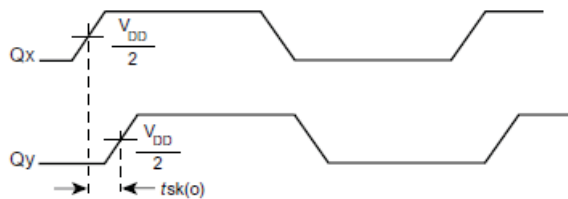
**2.5V OUTPUT LOAD AC TEST CIRCUIT**



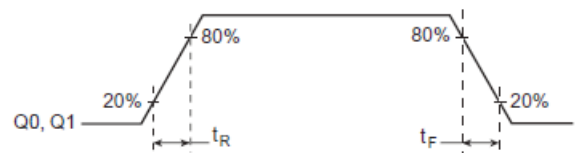
**DIFFERENTIAL INPUT LEVEL**



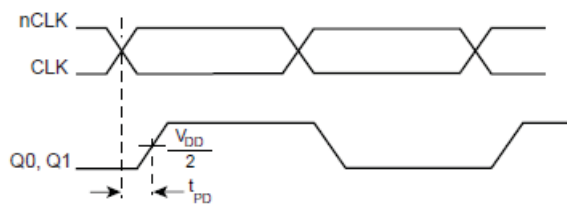
**PART-TO-PART SKEW**



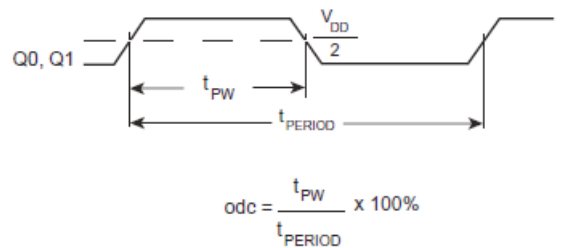
**OUTPUT SKEW**



**OUTPUT RISE/FALL TIME**



**PROPAGATION DELAY**



**OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD**

## APPLICATION INFORMATION

### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_{REF} = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the  $V_{REF}$  in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{DD} = 3.3V$ ,  $V_{REF}$  should be 1.25V and  $R2/R1 = 0.609$ .

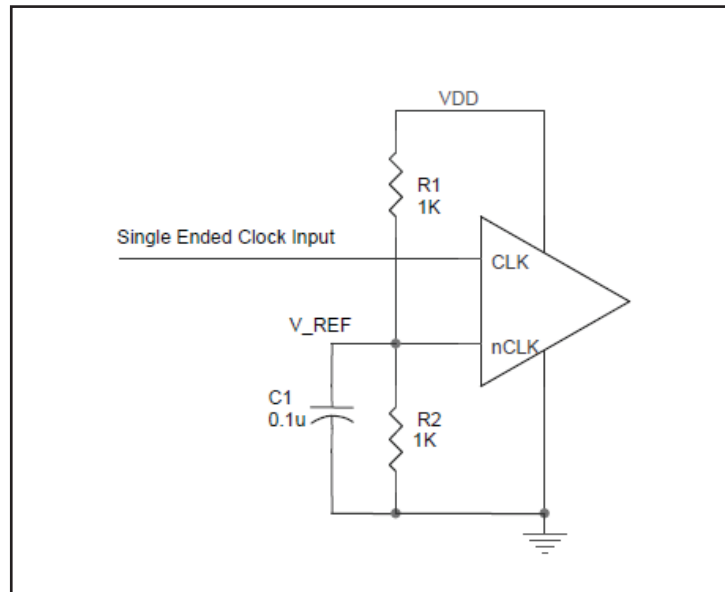


FIGURE 1. SINGLE ENDED SIGNAL DRIVING DIFFERENTIAL INPUT

### RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

#### INPUTS:

##### LVC MOS CONTROL PINS

All control pins have internal pullups or pulldowns; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

#### OUTPUTS:

##### LVC MOS OUTPUTS

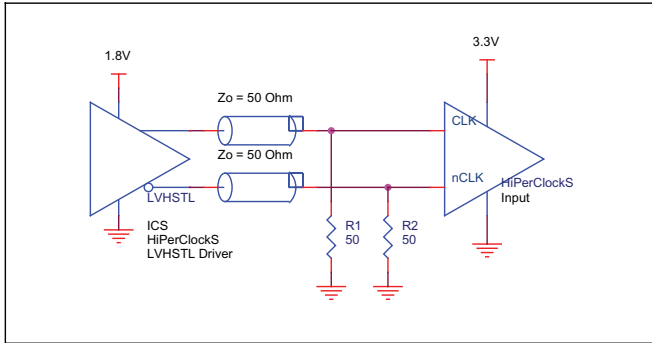
All unused LVC MOS output can be left floating. There should be no trace attached.



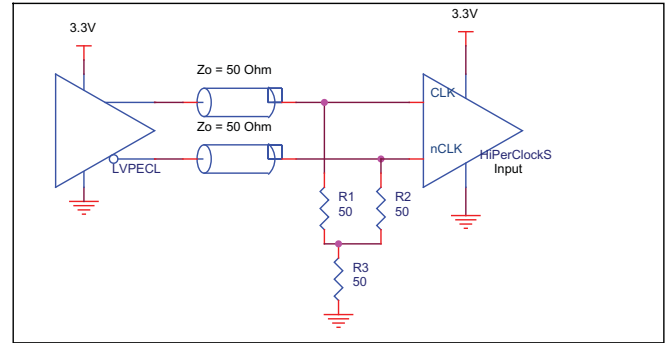
## DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both signals must meet the  $V_{PP}$  and  $V_{CMR}$  input requirements. Figures 2A to 2E show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only.

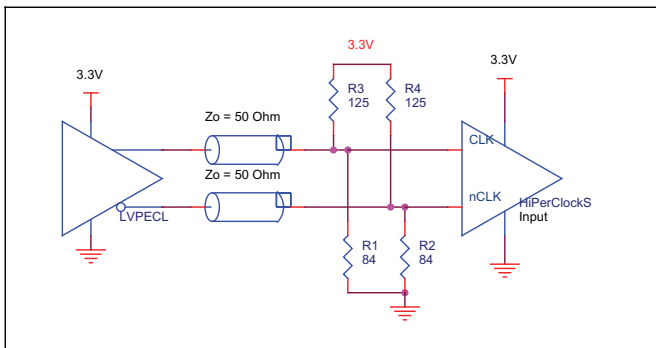
Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 2A*, the input termination applies for IDT HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.



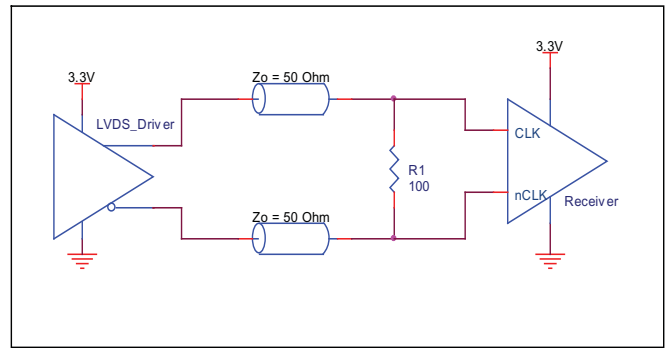
**FIGURE 2A. HiPerClockS CLK/nCLK INPUT DRIVEN BY IDT HiPerClockS LVHSTL DRIVER**



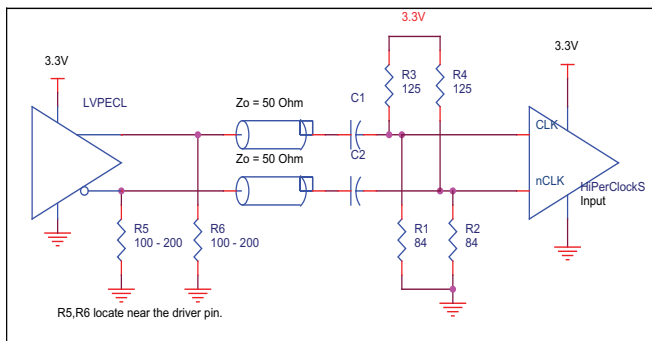
**FIGURE 2B. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER**



**FIGURE 2C. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER**



**FIGURE 2D. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER**



**FIGURE 2E. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER WITH AC COUPLE**

## RELIABILITY INFORMATION

TABLE 6.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 8 LEAD SOIC

| $\theta_{JA}$ by Velocity (Linear Feet per Minute) |         |         |        |
|--|---------|---------|--------|
|  | 0       | 200     | 500    |
| Single-Layer PCB, JEDEC Standard Test Boards       | 123°C/W | 110°C/W | 99°C/W |
| Multi-Layer PCB, JEDEC Standard Test Boards        | 103°C/W | 94°C/W  | 89°C/W |

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

### TRANSISTOR COUNT

The transistor count for 87021I is: 414

PACKAGE OUTLINE - M SUFFIX FOR 8 LEAD SOIC

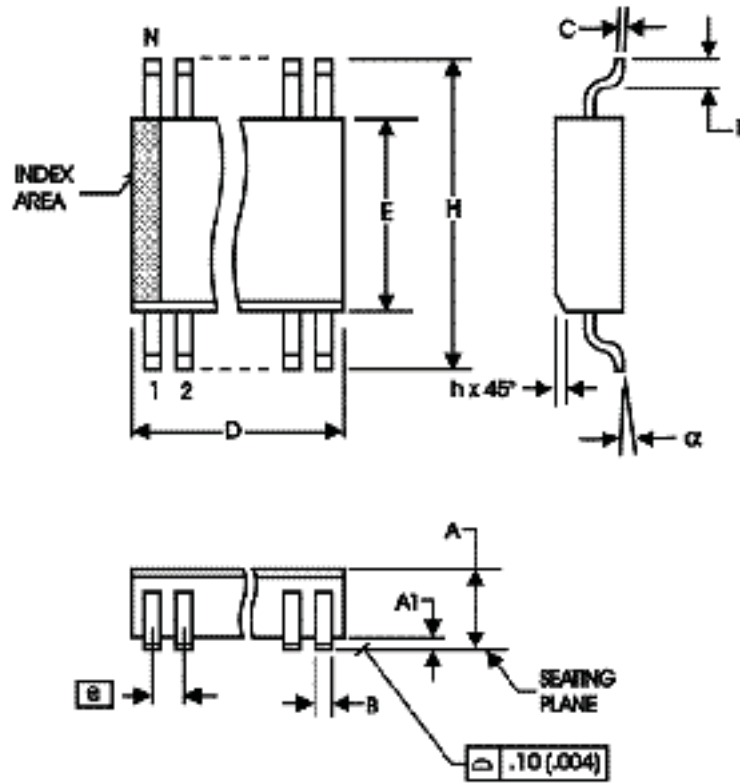


TABLE 7. PACKAGE DIMENSIONS

| SYMBOL | Millimeters |         |
|--------|-------------|---------|
|        | MINIMUM     | MAXIMUM |
| N      | 8           |         |
| A      | 1.35        | 1.75    |
| A1     | 0.10        | 0.25    |
| B      | 0.33        | 0.51    |
| C      | 0.19        | 0.25    |
| D      | 4.80        | 5.00    |
| E      | 3.80        | 4.00    |
| e      | 1.27 BASIC  |         |
| H      | 5.80        | 6.20    |
| h      | 0.25        | 0.50    |
| L      | 0.40        | 1.27    |
| α      | 0°          | 8°      |

Reference Document: JEDEC Publication 95, MS-012

**TABLE 8. ORDERING INFORMATION**

| <b>Part/Order Number</b> | <b>Marking</b> | <b>Package</b>          | <b>Shipping Packaging</b> | <b>Temperature</b> |
|--------------------------|----------------|-------------------------|---------------------------|--------------------|
| 87021AMILF               | 87021AIL       | 8 lead "Lead Free" SOIC | Tray                      | -40°C to +85°C     |
| 87021AMILFT              | 87021AIL       | 8 lead "Lead Free" SOIC | Tape and Reel             | -40°C to +85°C     |

| REVISION HISTORY SHEET |       |              |   |         |
|------------------------|-------|--------------|---|---------|
| Rev                    | Table | Page         | Description of Change   | Date    |
| B                      | T2    | 2            | Pin Characteristics Table - added R <sub>OUT</sub> row.   | 8/26/08 |
| B                      | T8    | 1<br>1<br>12 | Removed ICS from the part numbers where needed.<br>General Description - Removed the ICS chip and HiPerClockS.<br>Features Section - Removed reference to lead free packages.<br>Ordering Information - removed quantity from tape and reel. Deleted LF note below the table.<br>Updated header and footer. | 1-26-16 |



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